

# SSW1N50B / SSI1N50B

## 520V N-Channel MOSFET

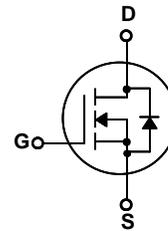
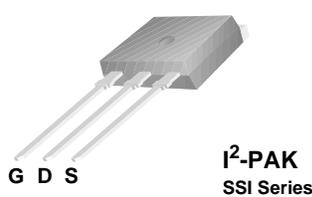
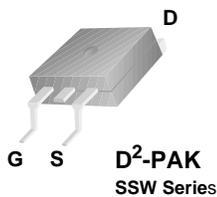
### General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies, power factor correction and electronic lamp ballasts based on half bridge.

### Features

- 1.5A, 520V,  $R_{DS(on)} = 5.3\Omega$  @  $V_{GS} = 10V$
- Low gate charge ( typical 8.3 nC)
- Low Crss ( typical 5.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	SSW1N50B / SSI1N50B	Units
V <sub>DSS</sub>	Drain-Source Voltage	520	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)	1.5	A
	- Continuous (T <sub>C</sub> = 100°C)	0.97	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	5.0	A
V <sub>GSS</sub>	Gate-Source Voltage	± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	100	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	1.5	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	3.6	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *	3.13	W
	Power Dissipation (T <sub>C</sub> = 25°C)	36	W
	- Derate above 25°C	0.29	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	--	3.44	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient *	--	40	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	--	62.5	°C/W

\* When mounted on the minimum pad size recommended (PCB Mount)

**Electrical Characteristics**T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	520	--	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	--	0.54	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V	--	--	10	μA
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C	--	--	100	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V	--	--	-100	nA

**On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	--	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.75 A	--	4.1	5.3	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 0.75 A (Note4)	--	1.8	--	S

**Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	--	260	340	pF
C <sub>oss</sub>	Output Capacitance		--	25	33	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	5.5	7.2	pF

**Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 1.5 A, R <sub>G</sub> = 25 Ω  (Note4, 5)	--	14	40	ns
t <sub>r</sub>	Turn-On Rise Time		--	40	90	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	35	80	ns
t <sub>f</sub>	Turn-Off Fall Time		--	35	80	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 1.5 A, V <sub>GS</sub> = 10 V  (Note4, 5)	--	8.3	11	nC
Q <sub>gs</sub>	Gate-Source Charge		--	1.5	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	3.4	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	1.5	A	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	5.0	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.5 A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.5 A,	--	230	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs (Note4)	--	0.94	--	μC

**Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 80mH, I<sub>AS</sub> = 1.5A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 1.5A, di/dt ≤ 300A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Characteristics

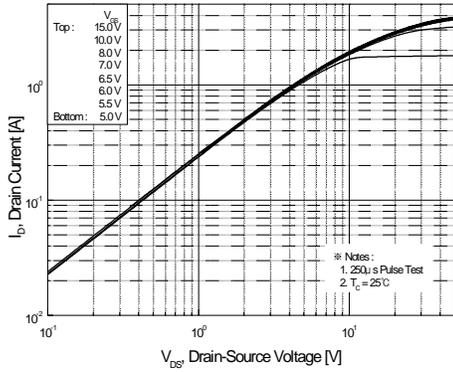


Figure 1. On-Region Characteristics

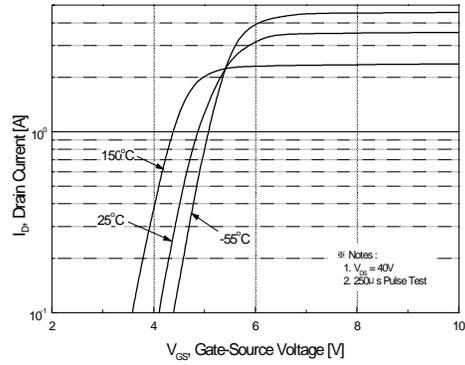


Figure 2. Transfer Characteristics

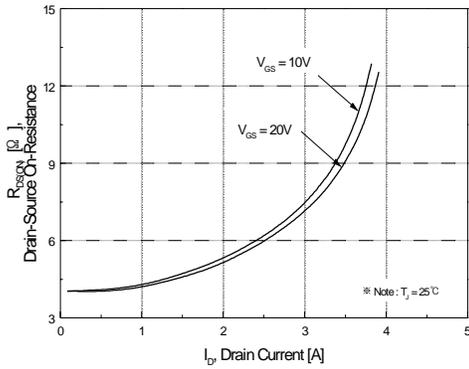


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

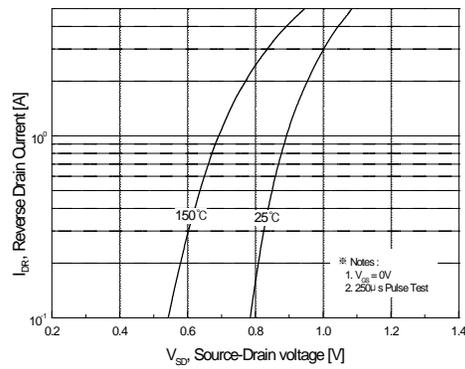


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

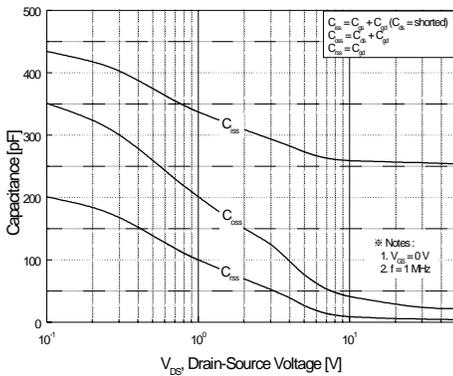


Figure 5. Capacitance Characteristics

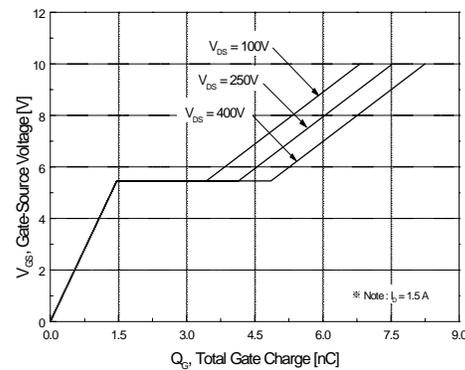


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

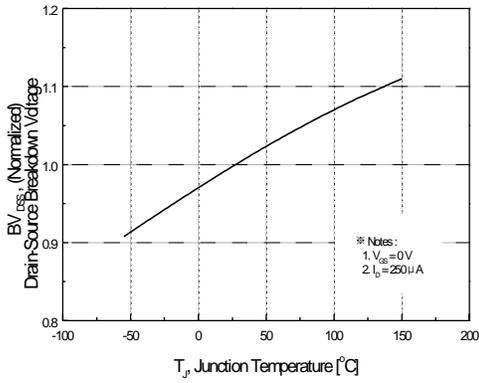


Figure 7. Breakdown Voltage Variation vs Temperature

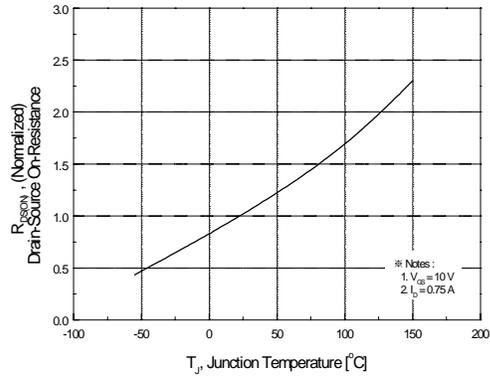


Figure 8. On-Resistance Variation vs Temperature

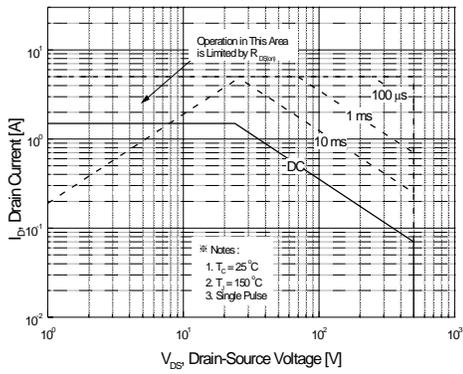


Figure 9. Maximum Safe Operating Area

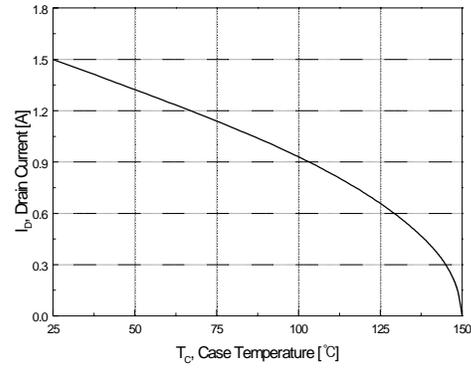


Figure 10. Maximum Drain Current vs Case Temperature

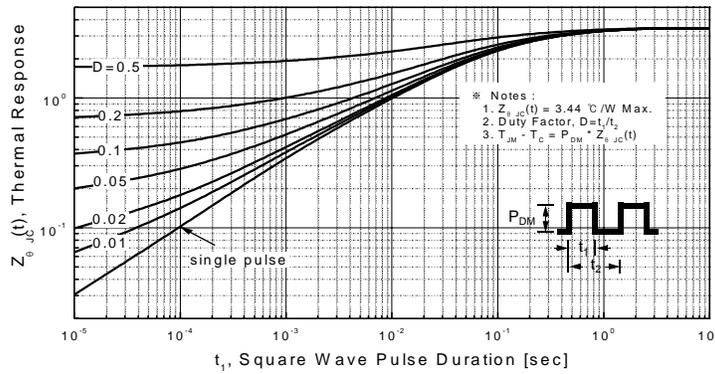
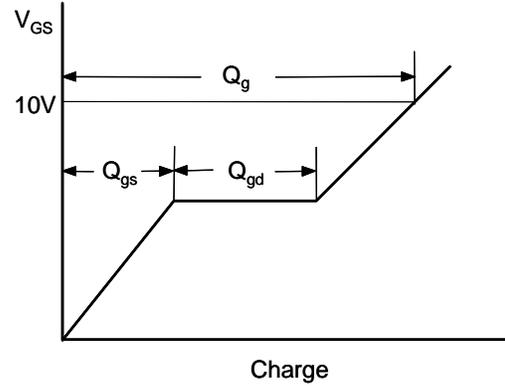
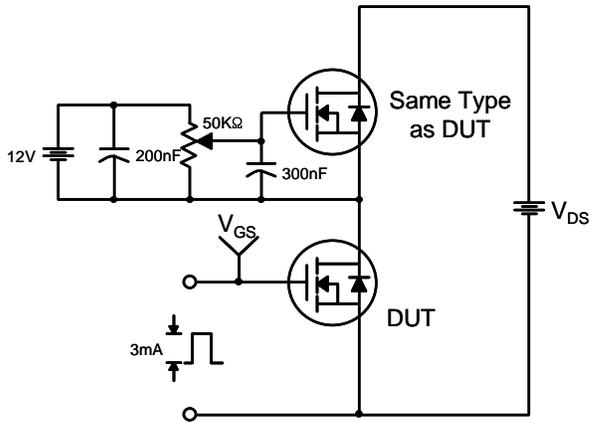
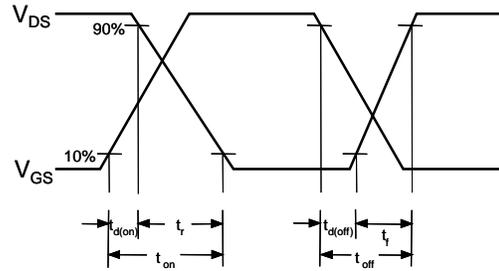
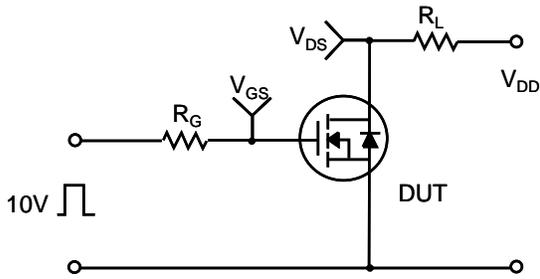


Figure 11. Transient Thermal Response Curve

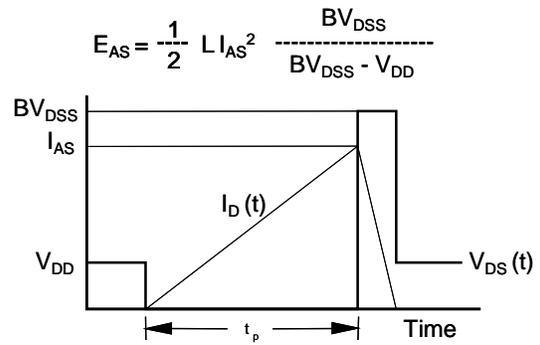
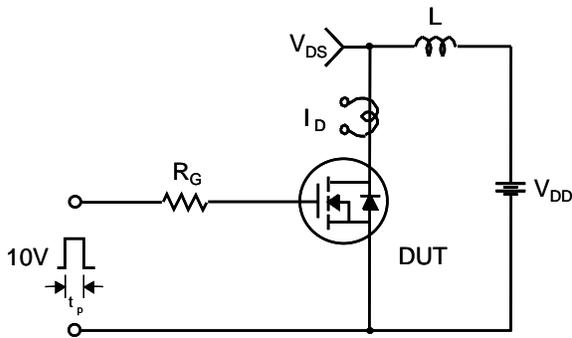
Gate Charge Test Circuit & Waveform



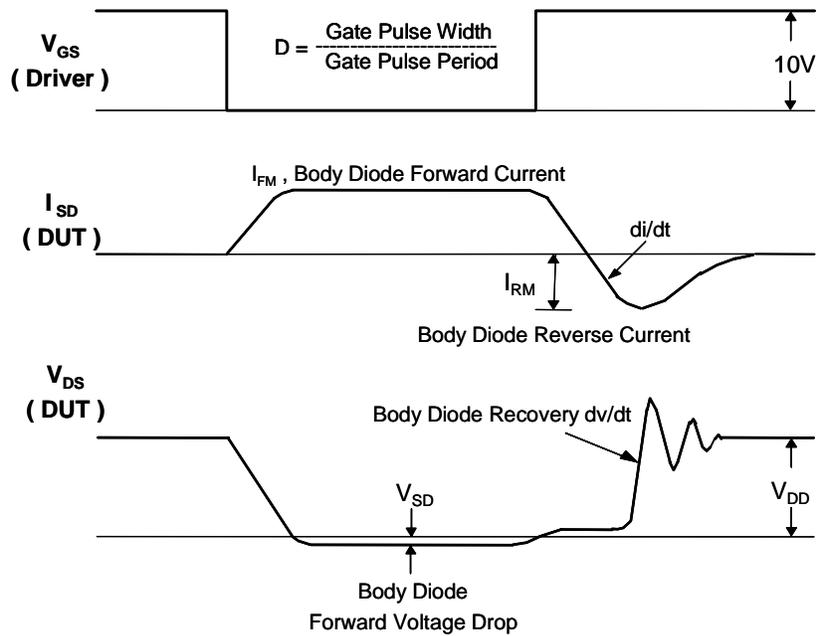
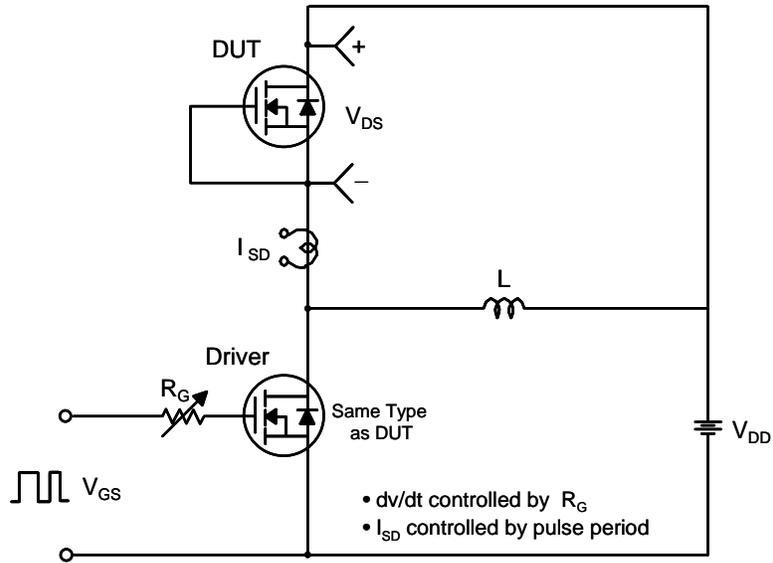
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

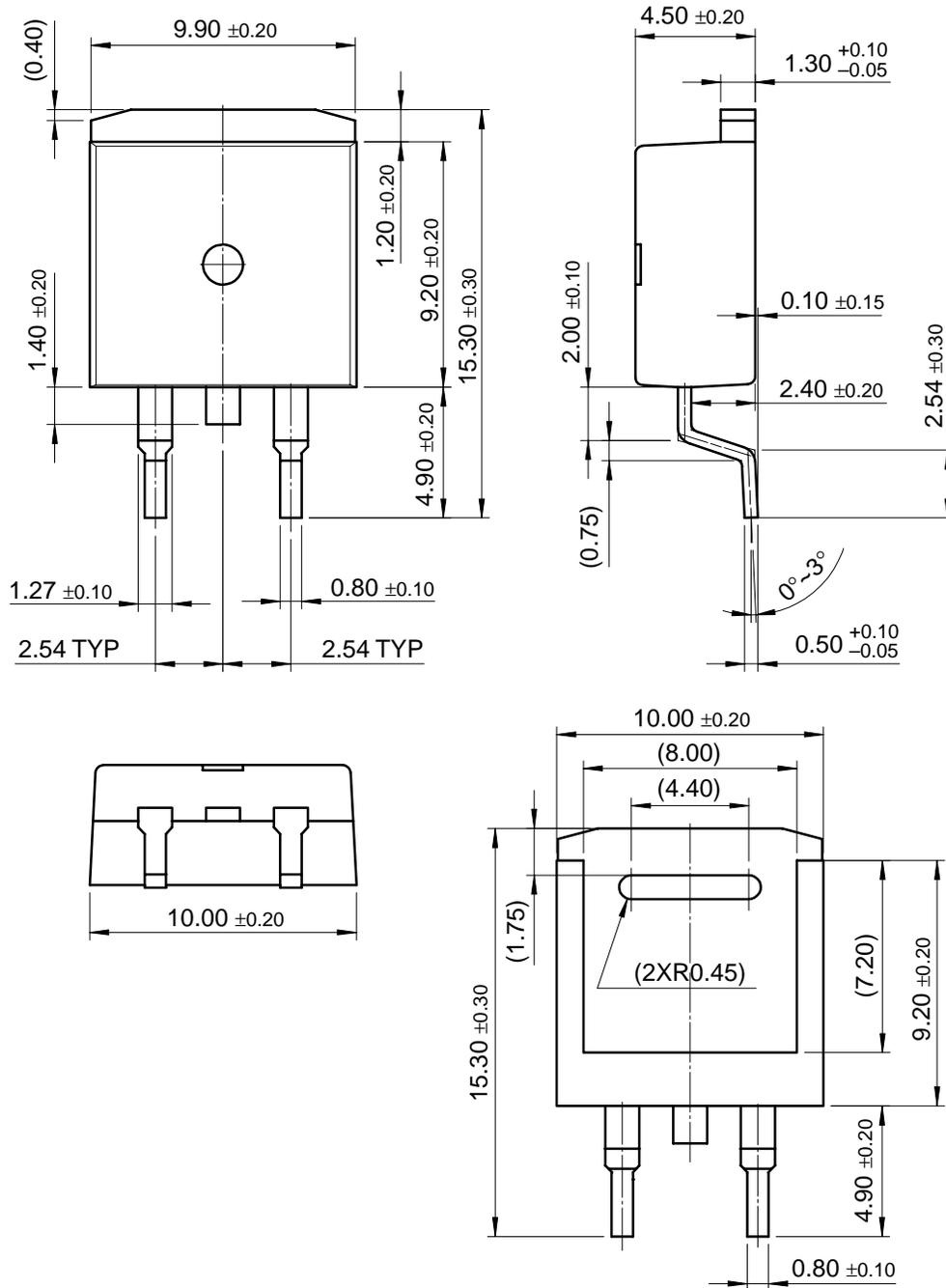


Peak Diode Recovery dv/dt Test Circuit & Waveforms



# Package Dimensions

## D<sup>2</sup>-PAK

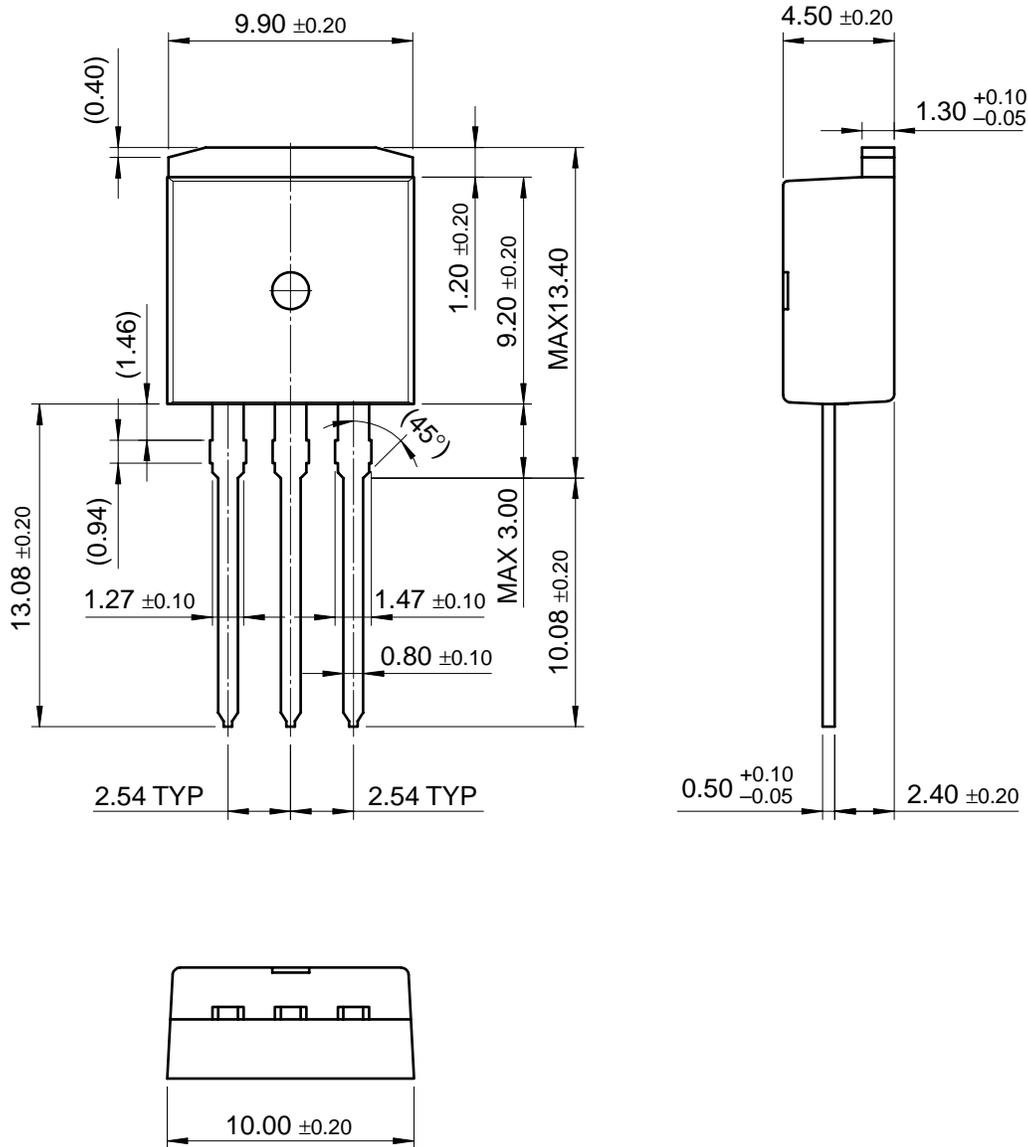


SSW1N50B / SSI1N50B

Dimensions in Millimeters

Package Dimensions (Continued)

# I<sup>2</sup>-PAK



SSW1N50B / SSI1N50B

Dimensions in Millimeters

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